







LM124, LM124A, LM224, LM224A, LM224K, LM224KA LM324, LM324A, LM324B, LM324K, LM324KA LM2902, LM2902B, LM2902K, LM2902KV, LM2902KAV SLOS066X - SEPTEMBER 1975 - REVISED MAY 2022

# LMx24, LMx24x, LMx24xx, LM2902, LM2902x, LM2902xx, LM2902xxx **Quadruple Operational Amplifiers**

#### 1 Features

- Wide supply range:
  - 3 V to 36 V (B, BA versions)
  - 3 V to 30 V (LMx24, LM2902V)
- Low input offset voltage maximum at 25°C:
  - 2 mV (BA versions LM2902A, LM124A)
  - 3 mV (B versions LMx24xA)
- Low input bias current maximum at 25°C:
  - 35 nA (B, BA versions)
- 2-kV ESD protection (HBM) (B, BA, K versions)
- Internal RF and EMI filter (B, BA versions)
- Low quiescent current of 175-µA/ch typical
- Common-mode input voltage range includes V<sub>CC</sub>
- Differential input voltage range equal to maximumrated supply voltage
- Open-loop differential voltage amplification: 100-V/mV typical
- On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

## 2 Applications

- Merchant network and server power supply units
- Multi-function printers
- Power supplies and mobile chargers
- Motor control: AC induction, brushed DC, brushless DC, high-voltage, low-voltage, permanent magnet, and stepper motor
- Desktop PC and motherboard
- Indoor and outdoor air conditioners
- Washers, dryers, and refrigerators
- AC inverters, string inverters, central inverters, and voltage frequency drives
- Uninterruptible power supplies

· Electronic point-of-sale systems

### 3 Description

These devices consist of four independent, high-gain, frequency-compensated, operational amplifiers that are designed specifically to operate from a single supply or split supply over a wide range of voltages.

#### **Device Information**

PART NUMBER <sup>(1)</sup>	PACKAGE	BODY SIZE (NOM)
LM324B <sup>(2)</sup> , LM324BA <sup>(2)</sup> , LM2902B <sup>(2)</sup> , LM2902BA <sup>(2)</sup> , LM324, LM324A, LM324K, LM324KA, LM2902, LM2902K, LM2902KV, LM2902KAV, LM224, LM224A, LM224K, LM224KA, LM124	SOIC (14)	8.65 mm × 3.91 mm
LM324B <sup>(2)</sup> , LM324BA <sup>(2)</sup> , LM2902B <sup>(2)</sup> , LM2902BA <sup>(2)</sup> , LM324, LM324A, LM324K, LM324KA, LM2902, LM2902K, LM2902KV, LM2902KAV, LM124	TSSOP (14)	5.00 mm × 4.40 mm
LM324, LM324A, LM324K, LM324KA, LM2902, LM2902K, LM224, LM224A, LM224K, LM224KA	PDIP (14)	19.30 mm × 6.35 mm
LM324, LM324A, LM324K, LM324KA, LM2902, LM2902K	SO (14)	9.20 mm × 5.30 mm
LM324A, LM2902K	SSOP (14)	6.20 mm × 5.30 mm
	CDIP (14)	19.56 mm × 6.67 mm
LM124A	CFP (14)	9.21 mm × 5.97 mm
	LCCC (20)	8.90 mm × 8.90 mm

- For all available packages, see the orderable addendum at the end of the data sheet.
- (2) This product is preview only.

#### **Family Comparison**

SPECIFICATION	LM324B LM324BA	LM2902B LM2902BA	LM324 LM324A	LM324K LM324KA	LM2902	LM2902K LM2902KV LM2902KAV	LM224 LM224A	LM224K LM224KA	LM124 LM124A	Units
Supply voltage	3 to 36	3 to 36	3 to 30	3 to 30	3 to 26	3 to 26 3 to 30 3 to 30	3 to 30	3 to 30	3 to 30	٧
Offset voltage (max, 25°C)	±3 ±2	±3 ±2	± 7 ± 3	± 7 ± 3	± 7	± 7 ± 7 ± 2	±5 ±3	±5 ±3	± 5 ± 2	mV
Input bias current (typ / max)	10 / 35	10 / 35	20 / 250 15 / 100	20 / 250 15 / 100	20 / 250	20 / 250	20 / 150 15 / 80	20 / 150 15 / 80	20 / 150 20 / 50	nA
ESD (HBM)	2000	2000	500	2000	500	2000	500	2000	500	V
Operating ambient temperature	-40 to 85	-40 to 125	0 to 70	0 to 70	-40 to 125	-40 to 125	−25 to 85	-25 to 85	-55 to 125	°C



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and BA versions13	Information20

## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision W (March 2015) to Revision X (May 2022)	Page
Updated Features to include the B and BA versions	1
Added application links to Applications section	1
Corrected available packages in the Device Information table	1
Added B and BA versions to Device Information table	
Updated package images in the Pin Configuration and Functions section changes	on to new format - no specification
• Renamed GND and Vcc to Vcc- and Vcc+, respectively, in the Pin Fund	
Added B and BA versions to Absolute Maximum Ratings table	
Added the B and BA versions to the ESD Ratings table	
<ul> <li>Added B and BA versions to Recommended Operating Conditions table</li> </ul>	
Added the Electrical Characteristics - LM324B and LM324BA table	
• Added the Electrical Characteristics - LM2902B and LM2902BA table	
Removed Documentation Support and Related Links in the Device and	Documentation Support section20
Changes from Revision V (January 2014) to Revision W (March 2014)	Page
Added Applications	
Added Device Information table	1



## **5 Pin Configuration and Functions**

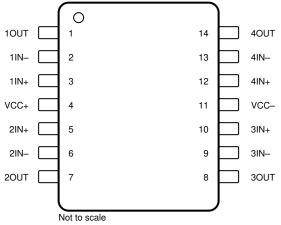


Figure 5-1. D, DB, J, N, NS, PW, and W Package 14-Pin SOIC, SSOP, CDIP, PDIP, SO, TSSOP, and CFP (Top View)

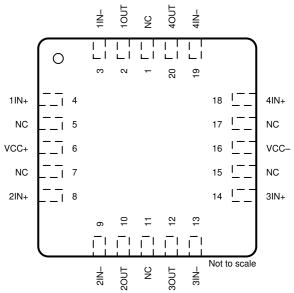


Figure 5-2. FK Package 20-Pin LCCC (Top View)

Table 5-1. Pin Functions

	PIN			
NAME	LCCC	SOIC, TSSOP, PDIP, SSOP, SO, CDIP, and CFP	I/O	DESCRIPTION
1IN-	3	2	I	Negative input
1IN+	4	3	I	Positive input
10UT	2	1	0	Output
2IN-	9	6	I	Negative input
2IN+	8	5	I	Positive input
2OUT	10	7	0	Output
3IN-	13	9	I	Negative input
3IN+	14	10	I	Positive input
3OUT	12	8	0	Output
4IN-	19	13	I	Negative input
4IN+	18	12	I	Positive input
4OUT	20	14	0	Output
V <sub>CC-</sub>	16	11	_	Negative (lowest) supply or ground (for single-supply operation)
NC	1, 5, 7, 11, 15, 17	_	_	Do not connect
V <sub>CC+</sub>	6	4	_	Positive (highest) supply



## **6 Specifications**

#### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			LM324BA, LM2902BA	LM	2902	LM324xx, LM224xx, LM2902xxx, LM124x		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
Supply voltage, V <sub>CC</sub> <sup>(2)</sup>			40		26	32		٧
Differential input voltage, V <sub>ID</sub> <sup>(3)</sup>			±40		±26	±32		٧
Input voltage, V <sub>I</sub> (either input)		-0.3	40	-0.3	26	-0.3	32	٧
Duration of output short circuit (one at (or below) T <sub>A</sub> = 25°C, V <sub>CC</sub> ≤ 15 V	tion of output short circuit (one amplifier) to ground below) $T_A = 25$ °C, $V_{CC} \le 15$ $V^{(4)}$		Unlimited		Unlimited		Unlimited	
Operating virtual junction temperatu	re, T <sub>J</sub>		150		150		150	°C
Case temperature for 60 seconds	FK package						260	°C
Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds	J or W package				300		300	°C
Storage temperature, T <sub>stg</sub>	•	-65	150	-65	150	-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- (2) All voltage values (except differential voltages and V<sub>CC</sub> specified for the measurement of I<sub>OS</sub>) are with respect to the network GND.
- 3) Differential voltages are at IN+, with respect to IN-.
- (4) Short circuits from outputs to VCC can cause excessive heating and eventual destruction.

### 6.2 ESD Ratings

			VALUE	UNIT	
1	3, LM324BA, LM2902B, LM290 K, LM324KA, LM2902K, LM290	, , , ,			
\ <u>\</u>	V <sub>(ESD)</sub> Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>		±2000	V
V(ESD)		Charged-device model (CDM), per JEDEC specification JESD22-C101	±1000	V	
LM124,	LM124A, LM224, LM224A, LN	1324, LM324A, LM2902			
V	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>		V	
V <sub>(ESD)</sub>	Lieurostano discriarge	Charged-device model (CDM), per JEDEC specification JESD22-C101	±1000	V	

<sup>(1)</sup> JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

#### **6.3 Recommended Operating Conditions**

over operating free-air temperature range (unless otherwise noted)

		LM324B, LM324BA, LM2902B, LM2902BA		LM29	02	LM324xx, LN LM2902xxx,	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	
V <sub>CC</sub> Supply voltage		3	36	3	26	3	30	V
V <sub>CM</sub> Common-mode v	oltage	0	V <sub>CC</sub> – 2	0	V <sub>CC</sub> – 2	0	V <sub>CC</sub> – 2	V
T <sub>A</sub> Operating free air temperature	LM124x					<b>–</b> 55	125	
	LM2902xxx, LM2902Bx	-40	125	-40	125			2.0
	LM324Bx	-40	85					°C
	LM224xx					-25	85	
	LM324xx					0	70	



#### 6.4 Thermal Information

			LMx24, LM2902					LMx24			
THERMAL METRIC(1)		D (SOIC)	DB (SSOP)	N (PDIP)	NS (SO)	PW (TSSOP)	FK (LCCC)	J (CDIP)	W (CFP)	UNIT	
		14 PINS	14 PINS	14 PINS	14 PINS	14 PINS	20 PINS	14 PINS	14 PINS		
R <sub>0</sub> JA (2) (3)	Junction-to- ambient thermal resistance	86	86	80	76	113	_	_	_	°C/W	
R <sub>0JC</sub> (4)	Junction-to-case (top) thermal resistance	_	_	_	_	_	5.61	15.05	14.65	°C/W	

- For more information about traditional and new thermal metrics, see the <u>Semiconductor and IC Package Thermal Metrics</u> application report.
- (2) Short circuits from outputs to VCC can cause excessive heating and eventual destruction.
- (3) Maximum power dissipation is a function of  $T_{J(max)}$ ,  $R_{\theta JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_{J(max)} T_A)/R_{\theta JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- (4) Maximum power dissipation is a function of  $T_{J(max)}$ ,  $R_{\theta JA}$ , and  $T_C$ . The maximum allowable power dissipation at any allowable case temperature is  $P_D = (T_{J(max)} T_C)/R_{\theta JC}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.

#### 6.5 Electrical Characteristics - LM324B and LM324BA

	PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
OFFSET VO	DLTAGE							
						±0.3	±3.0	
		LM324B		T <sub>A</sub> = -40°C to 85°C			±4.0	
Vos	Input offset voltage					±0.3	±2	mV
		LM324BA		T <sub>A</sub> = -40°C to 85°C			2.5	
dV <sub>OS</sub> /dT	Input offset voltage drift	R <sub>S</sub> = 0 Ω		T <sub>A</sub> = -40°C to 85°C		±7		μV/°C
	Input offset voltage versus			1A 10 0 10 00 0				
PSRR	power supply				65	100		dB
	Channel separation	f = 1 kHz to 20 kHz				120		dB
INPUT VOL	TAGE RANGE							
V	Common-mode voltage	V <sub>S</sub> = 3 V to 36 V			V-		(V+) – 1.5	V
V <sub>CM</sub>	range	V <sub>S</sub> = 5 V to 36 V		T <sub>A</sub> = -40°C to 85°C	V-		(V+) - 2	V
CMRR	Common-mode rejection	$(V-) \le V_{CM} \le (V+) - 1.5 \text{ V}$	V <sub>S</sub> = 3 V to 36 V		70	80		
JIVIKK	ratio	$(V-) \le V_{CM} \le (V+) - 2 V$	V <sub>S</sub> = 5 V to 36 V	T <sub>A</sub> = -40°C to 85°C	65	80		dB
NPUT BIAS	CURRENT							
	I					-10	-35	4
В	Input bias current			T <sub>A</sub> = -40°C to 85°C			-50	nA
dl <sub>OS</sub> /dT	Input offset current drift					10		pA/°C
						±0.5	±4	
los	Input offset current			T <sub>A</sub> = -40°C to 85°C			±5	nA
dl <sub>OS</sub> /dT	Input offset current drift			T <sub>A</sub> = -40°C to 85°C		10		pA/°C
NOISE								
E <sub>N</sub>	Input voltage noise	f = 0.1 to 10 Hz				3		μV <sub>PP</sub>
e <sub>N</sub>	Input voltage noise density	R <sub>S</sub> = 100 Ω, V <sub>I</sub> = 0 V, f = 1 kHz	(see Figure 8)			35		nV/√ <del>Hz</del>
	PACITANCE	0 11 7 7	· 3 · /					
Z <sub>ID</sub>	Differential					10    0.1		MΩ    pF
Z <sub>ICM</sub>	Common-mode					4    1.5		GΩ    pF
OPEN-LOO						.		- O11    P.
		45,45,44,44,45			50	100		
A <sub>OL</sub>	Open-loop voltage gain	$V_S = 15 \text{ V}, V_O = 1 \text{ V to } 11 \text{ V}, R_L $ (V-)	≥ ∠ KΩ, connected to	T <sub>A</sub> = -40°C to 85°C	25			V/mV
FREQUENC	Y RESPONSE			1 <sub>A</sub> 10 0 10 00 0				
GBW	Gain-bandwidth product	$R_L = 1 M\Omega$ , $C_L = 20 pF$ (see Fig.	qure 7)			1.2		MHz
SR	Slew rate	$R_L = 1 \text{ M}\Omega$ , $C_L = 30 \text{ pF}$ , $V_I = \pm 1$				0.5		V/µs
Θ <sub>m</sub>	Phase margin	$G = + 1$ , $R_L = 10k\Omega$ , $C_L = 20 pl$				56		ο ,
	Settling time	To 0.1%, $V_S = 5 \text{ V}$ , 2-V Step , (				4	$\longrightarrow$	- IIE
ts	Overload recovery time	$V_{IN} \times gain > V_{S}$	3 - 11, OL - 100 pi			10		μs
	Total harmonic distortion +					10		μs
THD+N	noise	$G = + 1$ , $f = 1$ kHz, $V_O = 3.53$ V	$V_{RMS}$ , $V_{S} = 36V$ , $R_{L} = 100$	0k, I <sub>OUT</sub> ≤ 50µA, BW = 80 kHz		0.001%		
OUTPUT	-			L				
v <sub>o</sub>				Ι <sub>ΟUT</sub> = -50 μΑ		1.35	1.5	V
V <sub>o</sub>	7	Positive Rail (V+)		I <sub>OUT</sub> = -1 mA		1.4	1.6	V
V <sub>O</sub>	1			I <sub>OUT</sub> = -5 mA		1.5	1.75	V
V <sub>O</sub>	Voltage output swing from rail			Ι <sub>ΟυΤ</sub> = 50 μΑ		100	150	mV
V <sub>o</sub>	7	Negative Dail (1/1)		I <sub>OUT</sub> = 1 mA		0.75	1	V
	+	Negative Rail (V-)	$V_S = 5 \text{ V, RL} \le 10 \text{ k}\Omega$					
Vo			connected to (V-)	$T_A = -40$ °C to 85°C		5	20	mV
		V <sub>S</sub> = 15 V; V <sub>O</sub> = V-; V <sub>ID</sub> = 1 V	Source		-20	-30		mA
		v <sub>5</sub> - 10 v, v <sub>0</sub> - v-, v <sub>ID</sub> - 1 v		T <sub>A</sub> = -40°C to 85°C	-10			mA
l <sub>o</sub>	Output current	V <sub>S</sub> = 15 V; V <sub>O</sub> = V+; V <sub>ID</sub> = -1	Sink		10	20		mA
		V	SIIIK	T <sub>A</sub> = -40°C to 85°C	5			mA
		V <sub>ID</sub> = -1 V; V <sub>O</sub> = (V-) + 200 mV	•		50	85		μΑ
I <sub>sc</sub>	Short-circuit current	V <sub>S</sub> = 20 V, (V+) = 10 V, (V-) = -	10 V, V <sub>O</sub> = 0 V			±40	±60	mA



## 6.5 Electrical Characteristics - LM324B and LM324BA (continued)

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
R <sub>O</sub>	Open-loop output impedance	f = 1 MHz, I <sub>O</sub> = 0 A			300		Ω
POWER SUP	PLY						
1	Quiescent current per	V <sub>S</sub> = 5 V; I <sub>O</sub> = 0 A	T <sub>A</sub> = -40°C to 85°C		175	300	μΑ
IQ	amplifier	V <sub>S</sub> = 36 V; I <sub>O</sub> = 0 A	T <sub>A</sub> = -40°C to 85°C		350	750	μΑ

#### 6.6 Electrical Characteristics - LM2902B and LM2902BA

	PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT	
OFFSET VO	DLTAGE								
						±0.3	±3.0		
		LM2902B		T <sub>A</sub> = -40°C to 125°C			±4.0		
Vos	Input offset voltage				-	±0.3	±2	mV	
		LM2902BA		T <sub>A</sub> = -40°C to 125°C			2.5		
dV <sub>OS</sub> /dT	Input offset voltage drift	R <sub>S</sub> = 0 Ω		T <sub>A</sub> = -40°C to 125°C		±7		μV/°C	
	Input offset voltage versus			1 A 10 0 10 10 0					
PSRR	power supply				65	100		dB	
	Channel separation	f = 1 kHz to 20 kHz				120		dB	
INPUT VOL	TAGE RANGE								
· · · · · · · · · · · · · · · · · · ·	Common-mode voltage	V <sub>S</sub> = 3 V to 36 V			V-		(V+) – 1.5	V	
V <sub>CM</sub>	range	V <sub>S</sub> = 5 V to 36 V		T <sub>A</sub> = -40°C to 125°C	V-		(V+) - 2	V	
CMDD	Common-mode rejection	$(V-) \le V_{CM} \le (V+) - 1.5 \text{ V}$	V <sub>S</sub> = 3 V to 36 V		70	80		40	
CMRR	ratio	$(V-) \le V_{CM} \le (V+) - 2 V$	V <sub>S</sub> = 5 V to 36 V	T <sub>A</sub> = -40°C to 125°C	65	80		dB	
INPUT BIAS	CURRENT								
	Innut biog growt					-10	-35	,- A	
В	Input bias current			T <sub>A</sub> = -40°C to 125°C			-50	nA	
dl <sub>OS</sub> /dT	Input offset current drift			T <sub>A</sub> = -40°C to 125°C		10		pA/°C	
						±0.5	±4		
los	Input offset current			T <sub>A</sub> = -40°C to 125°C			±5	nA	
dl <sub>OS</sub> /dT	Input offset current drift			T <sub>A</sub> = -40°C to 125°C		10		pA/°C	
NOISE					,			-	
E <sub>N</sub>	Input voltage noise	f = 0.1 to 10 Hz				3		μV <sub>PP</sub>	
e <sub>N</sub>	Input voltage noise density	R <sub>S</sub> = 100 Ω, V <sub>I</sub> = 0 V, f = 1 kHz	(see Figure 8)			35		nV/√Hz	
	PACITANCE	0 11 7 7	· 3 ·/						
Z <sub>ID</sub>	Differential					10    0.1		MΩ    pF	
Z <sub>ICM</sub>	Common-mode				-	4    1.5		GΩ    pF	
OPEN-LOO						7    1.0		O12    pi	
		45,45,44,44,45			50	100			
A <sub>OL</sub>	Open-loop voltage gain	$V_S = 15 \text{ V}, V_O = 1 \text{ V to } 11 \text{ V}, R_L \text{ (V-)}$	≥ 2 KΩ, connected to	T <sub>A</sub> = -40°C to 125°C	25	100		V/mV	
ERECHENC	Y RESPONSE			1 <sub>A</sub> 40 0 to 120 0					
GBW	Gain-bandwidth product	$R_L = 1 M\Omega$ , $C_L = 20 pF$ (see Fig.	gure 7)			1.2		MHz	
SR	Slew rate	$R_L = 1 \text{ M}\Omega$ , $C_L = 30 \text{ pF}$ , $V_I = \pm 1 \text{ M}\Omega$				0.5		V/µs	
		$G = + 1$ , $R_L = 10k\Omega$ , $C_L = 20 pl$				56		ν/μ5	
Θ <sub>m</sub>	Phase margin					4			
ts	Settling time	To 0.1%, V <sub>S</sub> = 5 V, 2-V Step , 0	5 = +1, C <sub>L</sub> = 100 pr					μs	
	Overload recovery time	V <sub>IN</sub> × gain > V <sub>S</sub>				10		μs	
THD+N	Total harmonic distortion + noise	$G = + 1$ , $f = 1$ kHz, $V_O = 3.53$ V	$V_{RMS}$ , $V_{S} = 36V$ , $R_{L} = 100$	0k, I <sub>OUT</sub> ≤ 50µA, BW = 80 kHz		0.001%			
OUTPUT		1			,				
Vo				I <sub>OUT</sub> = -50 μA		1.35	1.5	V	
V <sub>o</sub>	+	Positive Rail (V+)		I <sub>OUT</sub> = -1 mA		1.4	1.6	V	
V <sub>O</sub>	$\dashv$			I <sub>OUT</sub> = -5 mA		1.5	1.75	V	
V <sub>O</sub>	Voltage output swing from rail			Ι <sub>ΟυΤ</sub> = 50 μΑ		100	150	mV	
V <sub>O</sub>	- I all	N 6 B 760		I <sub>OUT</sub> = 1 mA		0.75	1	V	
	+	Negative Rail (V-)	$V_S = 5 \text{ V, RL} \le 10 \text{ k}\Omega$						
Vo			connected to (V–)	T <sub>A</sub> = -40°C to 125°C		5	20	mV	
		\( = 4E\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	Source		-20	-30		mA	
		$V_S = 15 \text{ V}; V_O = V_{-}; V_{ID} = 1 \text{ V}$	Source	T <sub>A</sub> = -40°C to 125°C	-10	-		mA	
lo	Output current	V <sub>S</sub> = 15 V; V <sub>O</sub> = V+; V <sub>ID</sub> = -1	Oin I		10	20		mA	
		V , 115	Sink	T <sub>A</sub> = -40°C to 125°C	5			mA	
		V <sub>ID</sub> = -1 V; V <sub>O</sub> = (V-) + 200 mV	1	14 10 11 12 1	50	85		μA	
I <sub>sc</sub>	Short-circuit current	V <sub>ID</sub> = -1 V; V <sub>O</sub> = (V-) + 200 mV V <sub>S</sub> = 20 V, (V+) = 10 V, (V-) = -				85 ±40	±60	μA mA	

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### 6.6 Electrical Characteristics - LM2902B and LM2902BA (continued)

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
R <sub>O</sub>	Open-loop output impedance	f = 1 MHz, I <sub>O</sub> = 0 A			300		Ω
POWER SUP	PPLY						
	Quiescent current per	V <sub>S</sub> = 5 V; I <sub>O</sub> = 0 A	T <sub>A</sub> = -40°C to 125°C		175	300	μΑ
IQ .	amplifier	V <sub>S</sub> = 36 V; I <sub>O</sub> = 0 A	T <sub>A</sub> = -40°C to 125°C		350	750	μΑ

#### 6.7 Electrical Characteristics for LMx24 and LM324K

at specified free-air temperature,  $V_{CC}$  = 5 V (unless otherwise noted)

				- (2)	LM1	24, LM224		LM32	4, LM324K		
	PARAMETER	TEST CON	DITIONS	T <sub>A</sub> <sup>(2)</sup>	MIN	TYP <sup>(3)</sup>	MAX	MIN	TYP <sup>(3)</sup>	MAX	UNIT
V	Input offset voltage	V <sub>CC</sub> = 5 V to MAX	, V <sub>IC</sub> = V <sub>ICR</sub> min,	25°C		3	5		3	7	mV
V <sub>IO</sub>	input offset voltage	V <sub>O</sub> = 1.4 V		Full range			7			9	mv
	Innuit offert ausmant	V = 4.4V		25°C		2	30		2	50	nA
I <sub>IO</sub>	Input offset current	V <sub>O</sub> = 1.4 V		Full range			100			150	ΠA
	Input bias current	V <sub>O</sub> = 1.4 V		25°C		-20	-150		-20	-250	nA
I <sub>IB</sub>	input bias current	V <sub>O</sub> = 1.4 V		Full range			-300			-500	ΠA
V <sub>ICR</sub>	Common-mode input voltage range	V <sub>CC</sub> = 5 V to MAX		25°C	0 to V <sub>CC</sub> – 1.5			0 to V <sub>CC</sub> – 1.5			V
VICR	Common-mode input voltage range	VCC - 3 V to WAX		Full range	0 to V <sub>CC</sub> – 2			$V_{CC} - 2$			•
		$R_L = 2 k\Omega$		25°C	V <sub>CC</sub> – 1.5			V <sub>CC</sub> – 1.5			
V <sub>OH</sub>	High-level output voltage	V <sub>CC</sub> = MAX	$R_L = 2 k\Omega$	Full range	26			26			V
		ACC - INIAX	R <sub>L</sub> ≥ 10 kΩ	Full range	27	28		27	28		
V <sub>OL</sub>	Low-level output voltage	$R_L \le 10 \text{ k}\Omega$		Full range		5	20		5	20	mV
A <sub>VD</sub>	Large-signal differential voltage	V <sub>CC+</sub> = 15 V, V <sub>O</sub> =	1 V to 11 V,	25°C	50	100		25	100		V/mV
AVD	amplification	$R_L \ge 2 k\Omega$		Full range	25			15			V/IIIV
CMRR	Common-mode rejection ratio	V <sub>IC</sub> = V <sub>ICR</sub> min		25°C	70	80		65	80		dB
k <sub>SVR</sub>	Supply-voltage rejection ratio $(\Delta V_{CC}/\Delta VIO)$			25°C	65	100		65	100		dB
V <sub>O1</sub> / V <sub>O2</sub>	Crosstalk attenuation	f = 1 kHz to 20 kH	z	25°C		120			120		dB
		V <sub>CC</sub> = 15 V,		25°C	-20	-30	-60	-20	-30	-60	
		$V_{ID} = 1 V$ , $V_{O} = 0$	Source	Full range	-10			-10			
Io	Output current	V <sub>CC</sub> = 15 V,		25°C	10	20		10	20		mA
		$V_{ID} = -1 \text{ V},$ $V_{O} = 15 \text{ V}$	Sink	Full range	5			5			
		$V_{ID} = -1 \text{ V}, V_{O} = 2$	00 mV	25°C	12	30		12	30		μA
Ios	Short-circuit output current	$V_{CC}$ at 5 V, $V_{O}$ = 0 $V_{CC}$ at -5 V	,	25°C		±40	±60		±40	±60	mA
		V <sub>O</sub> = 2.5 V, no loa	d	Full range		0.7	1.2		0.7	1.2	
Icc	Supply current (four amplifiers)	VMAY V05V		Full range		1.4	3		1.4	3	mA

All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified. MAX  $V_{\rm CC}$  for testing purposes is 26 V for LM2902 and 30 V for the others. Full range is  $-55^{\circ}{\rm C}$  to  $+125^{\circ}{\rm C}$  for LM124,  $-25^{\circ}{\rm C}$  to  $+85^{\circ}{\rm C}$  for LM224, and 0°C to 70°C for LM324.

<sup>(3)</sup> All typical values are at  $T_A = 25$ °C.



#### 6.8 Electrical Characteristics for LM2902 and LM2902V

at specified free-air temperature,  $V_{CC}$  = 5 V (unless otherwise noted)

			uzuo.uo(1)	- (2)	L	M2902		LI	M2902V		
	PARAMETER	TEST COND	ITIONS(1)	T <sub>A</sub> <sup>(2)</sup>	MIN	TYP <sup>(3)</sup>	MAX	MIN	TYP <sup>(3)</sup>	MAX	UNIT
			Non-A-suffix	25°C		3	7		3	7	
V <sub>IO</sub>	Input offset voltage	$V_{CC} = 5 \text{ V to MAX},$ $V_{IC} = V_{ICR} \text{min},$	devices	Full range			10			10	mV
VIO	input onset voltage	$V_0 = 1.4 \text{ V}$	A-suffix	25°C					1	2	IIIV
			devices	Full range						4	
$\Delta V_{IO}/\Delta T$	Input offset voltage temperature drift	R <sub>S</sub> = 0 Ω		Ful range					7		μV/°C
I <sub>IO</sub>	Input offset current	V <sub>O</sub> = 1.4 V		25°C		2	50		2	50	nA
IO	input onset current	V <sub>0</sub> = 1.4 V		Full range			300			150	ПА
$\Delta I_{IO}/\Delta T$	Input offset voltage temperature drift			Ful range					10		pA/°C
	Input bias current	V <sub>O</sub> = 1.4 V		25°C		-20	-250		-20	-250	nA
I <sub>IB</sub>	input bias current	V <sub>0</sub> - 1.4 V		Full range			-500			-500	IIA
V	Common-mode input voltage range	V <sub>CC</sub> = 5 V to MAX		25°C	0 to V <sub>CC</sub> – 1.5			0 to V <sub>CC</sub> – 1.5			V
V <sub>ICR</sub>	Common-mode input voltage range	VCC = 3 V to WAX		Full range	0 to V <sub>CC</sub> - 2			0 to V <sub>CC</sub> - 2			V
		R <sub>L</sub> = 10 kΩ		25°C	V <sub>CC</sub> – 1.5			V <sub>CC</sub> – 1.5			
$V_{OH}$	High-level output voltage	V - MAY	R <sub>L</sub> = 2 kΩ	Full range	22			26			V
		V <sub>CC</sub> = MAX	R <sub>L</sub> ≥ 10 kΩ	Full range	23	24		27			
V <sub>OL</sub>	Low-level output voltage	R <sub>L</sub> ≤ 10 kΩ		Full range		5	20		5	20	mV
	Large-signal differential voltage	V <sub>CC</sub> = 15 V,		25°C	25	100		25	100		
A <sub>VD</sub>	amplification	$V_O = 1 \text{ V to } 11 \text{ V},$ $R_L \ge 2 \text{ k}\Omega$		Full range	15			15			V/mV
CMRR	Common-mode rejection ratio	V <sub>IC</sub> = V <sub>ICR</sub> min		25°C	50	80		60	80		dB
k <sub>SVR</sub>	Supply-voltage rejection ratio $(\Delta V_{CC} / \Delta VIO)$			25°C	50	100		60	100		dB
V <sub>O1</sub> / V <sub>O2</sub>	Crosstalk attenuation	f = 1 kHz to 20 kHz		25°C		120			120		dB
		V <sub>CC</sub> = 15 V,		25°C	-20	-30	-60	-20	-30	-60	
		$V_{ID} = 1 V$ , $V_{O} = 0$	Source	Full range	-10			-10			A
Io	Output current	V <sub>CC</sub> = 15 V,		25°C	10	20		10	20		mA
		$V_{ID} = -1 \text{ V},$ $V_{O} = 15 \text{ V}$	Sink	Full range	5			5			
		V <sub>ID</sub> = -1 V, V <sub>O</sub> = 200 mV		25°C		30		12	40		μA
Ios	Short-circuit output current	V <sub>CC</sub> at 5 V, V <sub>O</sub> = 0,	V <sub>CC-</sub> at –5 V	25°C		±40	±60		±40	±60	mA
		V <sub>O</sub> = 2.5 V, no load		Full range		0.7	1.2		0.7	1.2	
I <sub>CC</sub>	Supply current (four amplifiers)	V <sub>CC</sub> = MAX, V <sub>O</sub> = 0 no load	.5 V <sub>CC</sub> ,	Full range		1.4	3		1.4	3	mA

<sup>(1)</sup> All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified. MAX V<sub>CC</sub> for testing purposes is 26 V for LM2902 and 32 V for LM2902V.

<sup>(2)</sup> Full range is -40°C to +125°C for LM2902.

<sup>(3)</sup> All typical values are at  $T_A = 25$ °C.

#### 6.9 Electrical Characteristics for LMx24A and LM324KA

at specified free-air temperature, V<sub>CC</sub> = 5 V (unless otherwise noted)

D4	DAMETER	TEST CON	DITIONO(1)	<b>-</b> (2)	L	M124A			LM224A		LM324A	, LM324	(A	UNIT
PA	ARAMETER	TEST CON	DITIONS	T <sub>A</sub> <sup>(2)</sup>	MIN	TYP <sup>(3)</sup>	MAX	MIN	TYP <sup>(3)</sup>	MAX	MIN	TYP <sup>(3)</sup>	MAX	UNII
.,	Input offset	V <sub>CC</sub> = 5 V to 3		25°C			2		2	3		2	3	.,
V <sub>IO</sub>	voltage	$V_{IC} = V_{ICR}min$ $V_{O} = 1.4 V$	,	Full range			4			4			5	mV
	Input offset	V <sub>O</sub> = 1.4 V		25°C			10		2	15		2	30	nA
I <sub>IO</sub>	current	V <sub>0</sub> = 1.4 V		Full range			30			30			75	IIA
I <sub>IB</sub>	Input bias	V <sub>O</sub> = 1.4 V		25°C			-50		-15	-80		-15	-100	nA
אוי	current	VO = 1.4 V		Full range			-100			-100			-200	11/5
V <sub>ICR</sub>	Common-mode input voltage	V <sub>CC</sub> = 30 V		25°C	0 to V <sub>CC</sub> - 1.5			0 to V <sub>CC</sub> – 1.5			0 to V <sub>CC</sub> – 1.5			V
VICR	range	VCC - 30 V		Full range	0 to V <sub>CC</sub> - 2			0 to V <sub>CC</sub> – 2			0 to V <sub>CC</sub> – 2			•
		$R_L = 2 k\Omega$		25°C	V <sub>CC</sub> - 1.5			V <sub>CC</sub> – 1.5			V <sub>CC</sub> – 1.5			
$V_{OH}$	High-level output voltage	V <sub>CC</sub> = 30 V	R <sub>L</sub> = 2 kΩ	Full range	26			26			26			V
		VCC 00 V	R <sub>L</sub> ≥ 10 kΩ	Full range	27			27	28		27	28		
V <sub>OL</sub>	Low-level output voltage	R <sub>L</sub> ≤ 10 kΩ		Full range			20		5	20		5	20	mV
	Large-signal	V <sub>CC</sub> = 15 V,		25°C	50	100		50	100		25	100		
A <sub>VD</sub>	differential voltage amplification	V <sub>O</sub> = 1 V to 11 V,		Full range	25			25			15			V/mV
CMRR	Common-mode rejection ratio	V <sub>IC</sub> = V <sub>ICR</sub> min		25°C	70			70	80		65	80		dB
k <sub>SVR</sub>	Supply-voltage rejection ratio (ΔV <sub>CC</sub> /ΔV <sub>IO</sub> )			25°C	65			65	100		65	100		dB
V <sub>O1</sub> / V <sub>O2</sub>	Crosstalk attenuation	f = 1 kHz to 20	) kHz	25°C		120			120			120		dB
		V <sub>CC</sub> = 15 V,		25°C	-20			-20	-30	-60	-20	-30	-60	
		$V_{ID} = 1 V,$ $V_{O} = 0$	Source	Full range	-10			-10			-10			
Io	Output current	V <sub>CC</sub> = 15 V,		25°C	10			10	20		1	20		mA
		$V_{ID} = -1 \text{ V},$ $V_{O} = 15 \text{ V}$	Sink	Full range	5			5			5			
		V <sub>ID</sub> = -1 V, V <sub>C</sub>	= 200 mV	25°C	12			12	30		12	30		μA
I <sub>OS</sub>	Short-circuit output current	V <sub>CC</sub> at 5 V, V <sub>C</sub> V <sub>O</sub> = 0	<sub>CC-</sub> at –5 V,	25°C		±40	±60		±40	±60		±40	±60	mA
		V <sub>O</sub> = 2.5 V, no	load	Full range		0.7	1.2		0.7	1.2		0.7	1.2	
I <sub>CC</sub>	Supply current (four amplifiers)	V <sub>CC</sub> = 30 V, V no load	<sub>O</sub> = 15 V,	Full range		1.4	3.		1.4	3		1.4	3	mA

- (1) All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.
- (2) Full range is  $-55^{\circ}$ C to  $+125^{\circ}$ C for LM124A,  $-25^{\circ}$ C to  $+85^{\circ}$ C for LM224A, and  $0^{\circ}$ C to  $70^{\circ}$ C for LM324A.
- (3) All typical values are at  $T_A = 25$ °C.

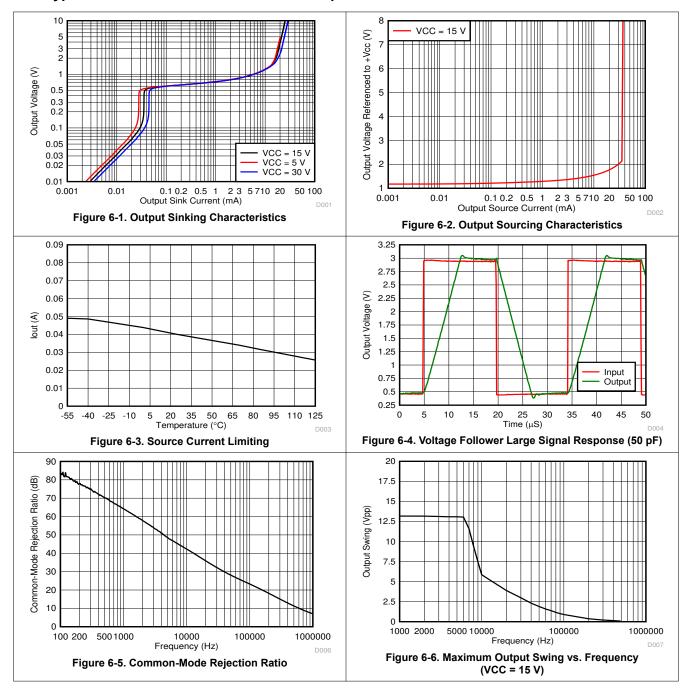
#### 6.10 Operating Conditions

 $V_{CC} = \pm 15 \text{ V}, T_A = 25^{\circ}\text{C}$ 

- 66	· · · · A - · ·			
	PARAMETER	TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain	$R_L = 1 M\Omega$ , $C_L = 30 pF$ , $V_I = \pm 10 V$ (see Figure 7-1)	0.5	V/µs
B <sub>1</sub>	Unity-gain bandwidth	$R_L = 1 M\Omega$ , $C_L = 20 pF$ (see Figure 7-1)	1.2	MHz
V <sub>n</sub>	Equivalent input noise voltage	$R_S = 100 \Omega$ , $V_I = 0 V$ , $f = 1 kHz$ (see Figure 7-2)	35	nV/√Hz

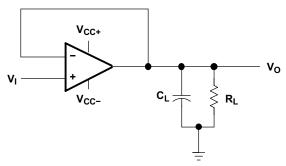


## 6.11 Typical Characteristics: All Devices Except B and BA versions





#### 7 Parameter Measurement Information



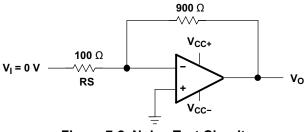


Figure 7-2. Noise-Test Circuit

Figure 7-1. Unity-Gain Amplifier



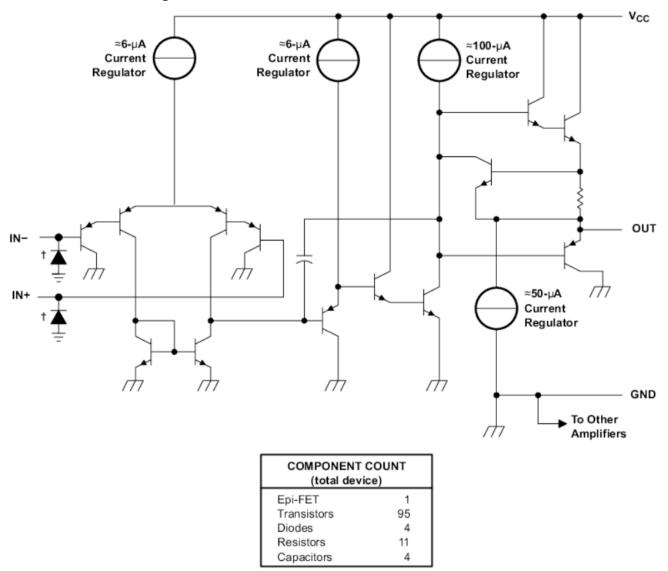
### 8 Detailed Description

#### 8.1 Overview

These devices consist of four independent high-gain frequency-compensated operational amplifiers that are designed specifically to operate from a single supply over a wide range of voltages. Operation from split supplies also is possible if the difference between the two supplies is 3 V to 36 V (B and BA versions), 3 V to 26 V (for LM2902 devices) or 3 V to 30V (for all other devices), and V<sub>CC</sub> is at least 1.5 V more positive than the input common-mode voltage. The low supply-current drain is independent of the magnitude of the supply voltage.

Applications include transducer amplifiers, DC amplification blocks, and all the conventional operational-amplifier circuits that now can be more easily implemented in single-supply-voltage systems. For example, the LM124 device can be operated directly from the standard 5-V supply that is used in digital systems and provides the required interface electronics, without requiring additional ±15-V supplies.

#### 8.2 Functional Block Diagram



ESD protection cells - available on B, BA, and K versions only

#### 8.3 Feature Description

#### 8.3.1 Unity-Gain Bandwidth

Gain bandwidth product is found by multiplying the measured bandwidth of an amplifier by the gain at which that bandwidth was measured. These devices have a high gain bandwidth of 1.2 MHz.

#### 8.3.2 Slew Rate

The slew rate is the rate at which an operational amplifier can change its output when there is a change on the input. These devices have a 0.5-V/µs slew rate.

#### 8.3.3 Input Common Mode Range

The valid common mode range is from device ground to  $V_{CC} - 1.5 \text{ V}$  ( $V_{CC} - 2 \text{ V}$  across temperature). Inputs may exceed  $V_{CC}$  up to the maximum  $V_{CC}$  without device damage. At least one input must be in the valid input common mode range for output to be correct phase. If both inputs exceed valid range then output phase is undefined. If either input is less than -0.3 V then input current should be limited to 1 mA and output phase is undefined.

#### 8.4 Device Functional Modes

These devices are powered on when the supply is connected. This device can be operated as a single supply operational amplifier or dual supply amplifier depending on the application.



### 9 Application and Implementation

#### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

#### 9.1 Application Information

The LMx24 and LM2902 operational amplifiers are useful in a wide range of signal conditioning applications. Inputs can be powered before VCC for flexibility in multiple supply circuits.

#### 9.2 Typical Application

A typical application for an operational amplifier in an inverting amplifier. This amplifier takes a positive voltage on the input, and makes it a negative voltage of the same magnitude. In the same manner, it also makes negative voltages positive.

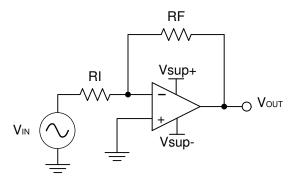


Figure 9-1. Application Schematic

## 9.2.1 Design Requirements

The supply voltage must be chosen such that it is larger than the input voltage range and output range. For instance, this application will scale a signal of  $\pm 0.5$  V to  $\pm 1.8$  V. Setting the supply at  $\pm 12$  V is sufficient to accommodate this application.

#### 9.2.2 Detailed Design Procedure

Determine the gain required by the inverting amplifier using Equation 1 and Equation 2:

$$A_{V} = \frac{VOUT}{VIN}$$
 (1)

$$A_{V} = \frac{1.8}{-0.5} = -3.6 \tag{2}$$

Once the desired gain is determined, choose a value for RI or RF. Choosing a value in the kilohm range is desirable because the amplifier circuit will use currents in the milliamp range. This ensures the part will not draw too much current. This example will choose 10 k $\Omega$  for RI which means 36 k $\Omega$  will be used for RF. This was determined by Equation 3.

$$A_{V} = -\frac{RF}{RI} \tag{3}$$

#### 9.2.3 Application Curve

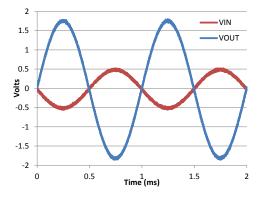


Figure 9-2. Input and Output Voltages of the Inverting Amplifier

### 10 Power Supply Recommendations

#### **CAUTION**

Supply voltages larger than 32 V for a single supply, or outside the range of  $\pm 16$  V for a dual supply can permanently damage the device (see the Section 6.1).

Place 0.1-µF bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high impedance power supplies. For more detailed information on bypass capacitor placement, refer to the Section 11.

## 11 Layout

## 11.1 Layout Guidelines

For best operational performance of the device, use good PCB layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole, as well as the
  operational amplifier. Bypass capacitors are used to reduce the coupled noise by providing low impedance
  power sources local to the analog circuitry.
  - Connect low-ESR, 0.1-µF ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most-effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current.
- To reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If it is not possible to keep them separate, it is much better to cross the sensitive trace perpendicular as opposed to in parallel with the noisy trace.
- Place the external components as close to the device as possible. Keeping RF and RG close to the inverting input minimizes parasitic capacitance, as shown in Section 11.2.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.



#### 11.2 Layout Examples

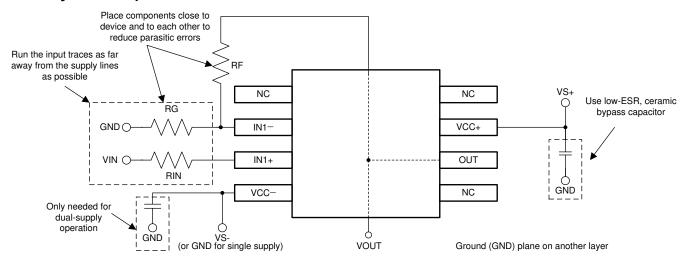


Figure 11-1. Operational Amplifier Board Layout for Noninverting Configuration

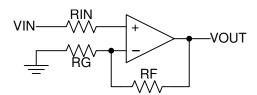


Figure 11-2. Operational Amplifier Schematic for Noninverting Configuration

### 12 Device and Documentation Support

### 12.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

#### 12.2 Support Resources

TI E2E<sup>™</sup> support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

#### 12.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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#### 12.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 12.5 Glossary

TI Glossary

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.





## **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-7704301VCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7704301VC A LM124JQMLV	Samples
5962-9950403V9B	ACTIVE	XCEPT	KGD	0	100	RoHS & Green	Call TI	N / A for Pkg Type	-55 to 125		Samples
5962-9950403VCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9950403VC A LM124AJQMLV	Samples
77043012A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	77043012A LM124FKB	Samples
7704301CA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7704301CA LM124JB	Samples
7704301DA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7704301DA LM124WB	Samples
77043022A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	77043022A LM124AFKB	Samples
7704302CA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7704302CA LM124AJB	Samples
7704302DA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7704302DA LM124AWB	Samples
JM38510/11005BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510 /11005BCA	Samples
LM124AFKB	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	77043022A LM124AFKB	Samples
LM124AJ	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	LM124AJ	Samples
LM124AJB	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7704302CA LM124AJB	Samples
LM124AWB	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7704302DA LM124AWB	Samples
LM124D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM124	Samples
LM124DG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM124	Samples





Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM124DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM124	Samples
LM124DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM124	Samples
LM124FKB	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	77043012A LM124FKB	Samples
LM124J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	LM124J	Samples
LM124JB	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7704301CA LM124JB	Samples
LM124W	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	LM124W	Samples
LM124WB	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7704301DA LM124WB	Samples
LM224AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224A	Samples
LM224ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-25 to 85	LM224A	Samples
LM224ADRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224A	Samples
LM224ADRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224A	Samples
LM224AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-25 to 85	LM224AN	Samples
LM224D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224	Samples
LM224DG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224	Samples
LM224DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-25 to 85	LM224	Samples
LM224DRG3	ACTIVE	SOIC	D	14	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-25 to 85	LM224	Samples
LM224DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224	Samples
LM224KAD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224KA	Samples
LM224KADG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224KA	Samples
LM224KADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224KA	Samples





Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM224KADRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224KA	Samples
LM224KAN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-25 to 85	LM224KAN	Samples
LM224KDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224K	Samples
LM224KDRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM224K	Samples
LM224KN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-25 to 85	LM224KN	Samples
LM224N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-25 to 85	LM224N	Samples
LM224NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-25 to 85	LM224N	Samples
LM2902D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902	Samples
LM2902DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	LM2902	Samples
LM2902DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902	Samples
LM2902DRG3	ACTIVE	SOIC	D	14	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	LM2902	Samples
LM2902DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902	Samples
LM2902KAVQDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KA	Samples
LM2902KAVQDRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KA	Samples
LM2902KAVQPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KA	Samples
LM2902KAVQPWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KA	Samples
LM2902KD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902K	Samples
LM2902KDB	ACTIVE	SSOP	DB	14	80	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902K	Samples
LM2902KDG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902K	Samples
LM2902KDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902K	Samples
LM2902KN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 125	LM2902KN	Samples





Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM2902KNSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902K	Samples
LM2902KNSRG4	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902K	Samples
LM2902KPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902K	Samples
LM2902KPWE4	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902K	Samples
LM2902KPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902K	Samples
LM2902KVQDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KV	Samples
LM2902KVQDRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KV	Samples
LM2902KVQPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KV	Samples
LM2902KVQPWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902KV	Samples
LM2902N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU   SN	N / A for Pkg Type	-40 to 125	LM2902N	Samples
LM2902NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 125	LM2902N	Samples
LM2902NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2902	Samples
LM2902PW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902	Samples
LM2902PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 125	L2902	Samples
LM2902PWRE4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902	Samples
LM2902PWRG3	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	SN	Level-1-260C-UNLIM	-40 to 125	L2902	Samples
LM2902PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2902	Samples
LM324AD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A	Samples
LM324ADBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A	Samples
LM324ADE4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A	Samples
LM324ADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	0 to 70	LM324A	Samples





Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM324ADRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A	Samples
LM324ADRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A	Samples
LM324AN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	LM324AN	Samples
LM324ANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A	Samples
LM324ANSRG4	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324A	Samples
LM324APW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324A	Samples
LM324APWE4	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324A	Samples
LM324APWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	0 to 70	L324A	Samples
LM324APWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324A	Samples
LM324D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324	Samples
LM324DE4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324	Samples
LM324DG4	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324	Samples
LM324DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	0 to 70	LM324	Samples
LM324DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324	Samples
LM324DRG3	ACTIVE	SOIC	D	14	2500	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	LM324	Samples
LM324DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324	Samples
LM324KAD	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324KA	Samples
LM324KADR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324KA	Samples
LM324KADRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324KA	Samples
LM324KAN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	LM324KAN	Samples
LM324KANSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324KA	Samples





Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samı
LM324KAPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324KA	Samp
LM324KAPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324KA	Samp
LM324KAPWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324KA	Samp
LM324KDR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324K	Samp
LM324KN	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	LM324KN	Samj
LM324KNSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324K	Samj
LM324KPW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324K	Sam
LM324KPWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324K	Sam
LM324N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU   SN	N / A for Pkg Type	0 to 70	LM324N	Sam
LM324NE3	ACTIVE	PDIP	N	14	25	RoHS & Non-Green	SN	N / A for Pkg Type	0 to 70	LM324N	Sam
LM324NE4	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	LM324N	Sam
LM324NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324	Sam
LM324NSRE4	ACTIVE	so	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324	Sam
LM324NSRG4	ACTIVE	so	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM324	Sam
LM324PW	ACTIVE	TSSOP	PW	14	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324	Sam
LM324PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU   SN	Level-1-260C-UNLIM	0 to 70	L324	Sam
LM324PWRE4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324	Sam
LM324PWRG3	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	SN	Level-1-260C-UNLIM	0 to 70	L324	Sam
LM324PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	L324	Sam
M38510/11005BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510 /11005BCA	Sam
PLM2902BIPWR	ACTIVE	TSSOP	PW	14	3000	TBD	Call TI	Call TI	-40 to 125		Sam

## **PACKAGE OPTION ADDENDUM**

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
PLM324BIPWR	ACTIVE	TSSOP	PW	14	3000	TBD	Call TI	Call TI	-40 to 85		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF LM124. LM124-SP. LM124M. LM2902. LM2902B:

Catalog: LM124, LM124

## PACKAGE OPTION ADDENDUM

www.ti.com 10-Jun-2022

• Automotive : LM2902-Q1, LM2902B-Q1

● Enhanced Product : LM2902-EP

• Military : LM124M, LM124M

• Space : LM124-SP, LM124-SP

#### NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application



www.ti.com 3-Jun-2022

#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM124DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224ADR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.1	8.0	16.0	Q1
LM224ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224ADRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224ADRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.1	8.0	16.0	Q1
LM224DRG3	SOIC	D	14	2500	330.0	17.5	6.4	9.05	2.1	8.0	16.0	Q1
LM224DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.1	8.0	16.0	Q1
LM224DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224KADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM224KDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2902DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.1	8.0	16.0	Q1
LM2902DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2902DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2902DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.1	8.0	16.0	Q1



# **PACKAGE MATERIALS INFORMATION**

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2902DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2902DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2902KAVQPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KAVQPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2902KNSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM2902KPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KVQPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902KVQPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902NSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM2902PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902PWRG3	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2902PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324ADBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
LM324ADR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.1	8.0	16.0	Q1
LM324ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324ADRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324ANSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM324APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324APWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.1	8.0	16.0	Q1
LM324DRG3	SOIC	D	14	2500	330.0	17.5	6.4	9.05	2.1	8.0	16.0	Q1
LM324DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.1	8.0	16.0	Q1
LM324DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324KADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324KANSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM324KAPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324KDR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM324KNSR	so	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM324KPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM324PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324PWRG3	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM324PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1





\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM124DR	SOIC	D	14	2500	350.0	350.0	43.0
LM224ADR	SOIC	D	14	2500	364.0	364.0	27.0
LM224ADR	SOIC	D	14	2500	356.0	356.0	35.0
LM224ADRG4	SOIC	D	14	2500	356.0	356.0	35.0
LM224ADRG4	SOIC	D	14	2500	340.5	336.1	32.0
LM224DR	SOIC	D	14	2500	356.0	356.0	35.0
LM224DR	SOIC	D	14	2500	364.0	364.0	27.0
LM224DRG3	SOIC	D	14	2500	333.2	345.9	28.6
LM224DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM224DRG4	SOIC	D	14	2500	356.0	356.0	35.0
LM224KADR	SOIC	D	14	2500	356.0	356.0	35.0
LM224KDR	SOIC	D	14	2500	356.0	356.0	35.0
LM2902DR	SOIC	D	14	2500	364.0	364.0	27.0
LM2902DR	SOIC	D	14	2500	356.0	356.0	35.0
LM2902DR	SOIC	D	14	2500	340.5	336.1	32.0
LM2902DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM2902DRG4	SOIC	D	14	2500	340.5	336.1	32.0
LM2902DRG4	SOIC	D	14	2500	356.0	356.0	35.0



# **PACKAGE MATERIALS INFORMATION**

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2902KAVQPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2902KAVQPWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2902KDR	SOIC	D	14	2500	356.0	356.0	35.0
LM2902KNSR	so	NS	14	2000	356.0	356.0	35.0
LM2902KPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2902KVQPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2902KVQPWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2902NSR	so	NS	14	2000	356.0	356.0	35.0
LM2902PWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM2902PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM2902PWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
LM2902PWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
LM324ADBR	SSOP	DB	14	2000	356.0	356.0	35.0
LM324ADR	SOIC	D	14	2500	364.0	364.0	27.0
LM324ADR	SOIC	D	14	2500	356.0	356.0	35.0
LM324ADRG4	SOIC	D	14	2500	356.0	356.0	35.0
LM324ANSR	SO	NS	14	2000	356.0	356.0	35.0
LM324APWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM324APWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM324APWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
LM324DR	SOIC	D	14	2500	356.0	356.0	35.0
LM324DR	SOIC	D	14	2500	364.0	364.0	27.0
LM324DRG3	SOIC	D	14	2500	333.2	345.9	28.6
LM324DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM324DRG4	SOIC	D	14	2500	340.5	336.1	32.0
LM324DRG4	SOIC	D	14	2500	356.0	356.0	35.0
LM324KADR	SOIC	D	14	2500	356.0	356.0	35.0
LM324KANSR	so	NS	14	2000	356.0	356.0	35.0
LM324KAPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM324KDR	SOIC	D	14	2500	356.0	356.0	35.0
LM324KNSR	so	NS	14	2000	356.0	356.0	35.0
LM324KPWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM324NSR	so	NS	14	2000	356.0	356.0	35.0
LM324PWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM324PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
LM324PWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
LM324PWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0



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#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9950403VCA	J	CDIP	14	1	506.98	15.24	13440	NA
77043012A	FK	LCCC	20	1	506.98	12.06	2030	NA
7704301DA	W	CFP	14	1	506.98	26.16	6220	NA
77043022A	FK	LCCC	20	1	506.98	12.06	2030	NA
7704302DA	W	CFP	14	1	506.98	26.16	6220	NA
LM124AFKB	FK	LCCC	20	1	506.98	12.06	2030	NA
LM124AWB	W	CFP	14	1	506.98	26.16	6220	NA
LM124D	D	SOIC	14	50	505.46	6.76	3810	4
LM124DG4	D	SOIC	14	50	505.46	6.76	3810	4
LM124FKB	FK	LCCC	20	1	506.98	12.06	2030	NA
LM124W	W	CFP	14	1	506.98	26.16	6220	NA
LM124WB	W	CFP	14	1	506.98	26.16	6220	NA
LM224AD	D	SOIC	14	50	506.6	8	3940	4.32
LM224AN	N	PDIP	14	25	506	13.97	11230	4.32
LM224D	D	SOIC	14	50	506.6	8	3940	4.32
LM224DG4	D	SOIC	14	50	506.6	8	3940	4.32
LM224KAD	D	SOIC	14	50	506.6	8	3940	4.32
LM224KADG4	D	SOIC	14	50	506.6	8	3940	4.32
LM224KAN	N	PDIP	14	25	506	13.97	11230	4.32
LM224KN	N	PDIP	14	25	506	13.97	11230	4.32
LM224N	N	PDIP	14	25	506	13.97	11230	4.32
LM224NE4	N	PDIP	14	25	506	13.97	11230	4.32
LM2902D	D	SOIC	14	50	506.6	8	3940	4.32
LM2902KD	D	SOIC	14	50	506.6	8	3940	4.32
LM2902KDB	DB	SSOP	14	80	530	10.5	4000	4.1
LM2902KDG4	D	SOIC	14	50	506.6	8	3940	4.32
LM2902KN	N	PDIP	14	25	506	13.97	11230	4.32
LM2902KPW	PW	TSSOP	14	90	530	10.2	3600	3.5
LM2902KPWE4	PW	TSSOP	14	90	530	10.2	3600	3.5



# **PACKAGE MATERIALS INFORMATION**

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
LM2902N	N	PDIP	14	25	506	13.97	11230	4.32
LM2902N	N	PDIP	14	25	506.1	9	600	5.4
LM2902NE4	N	PDIP	14	25	506	13.97	11230	4.32
LM2902PW	PW	TSSOP	14	90	530	10.2	3600	3.5
LM324AD	D	SOIC	14	50	506.6	8	3940	4.32
LM324ADE4	D	SOIC	14	50	506.6	8	3940	4.32
LM324AN	N	PDIP	14	25	506	13.97	11230	4.32
LM324AN	N	PDIP	14	25	506	13.97	11230	4.32
LM324APW	PW	TSSOP	14	90	530	10.2	3600	3.5
LM324APWE4	PW	TSSOP	14	90	530	10.2	3600	3.5
LM324D	D	SOIC	14	50	507	8	3940	4.32
LM324D	D	SOIC	14	50	506.6	8	3940	4.32
LM324DE4	D	SOIC	14	50	507	8	3940	4.32
LM324DE4	D	SOIC	14	50	506.6	8	3940	4.32
LM324DG4	D	SOIC	14	50	507	8	3940	4.32
LM324DG4	D	SOIC	14	50	506.6	8	3940	4.32
LM324KAD	D	SOIC	14	50	506.6	8	3940	4.32
LM324KAN	N	PDIP	14	25	506	13.97	11230	4.32
LM324KAN	N	PDIP	14	25	506	13.97	11230	4.32
LM324KAPW	PW	TSSOP	14	90	530	10.2	3600	3.5
LM324KN	N	PDIP	14	25	506	13.97	11230	4.32
LM324KN	N	PDIP	14	25	506	13.97	11230	4.32
LM324KPW	PW	TSSOP	14	90	530	10.2	3600	3.5
LM324N	N	PDIP	14	25	506	13.97	11230	4.32
LM324N	N	PDIP	14	25	506	13.97	11230	4.32
LM324N	N	PDIP	14	25	506.1	9	600	5.4
LM324NE3	N	PDIP	14	25	506.1	9	600	5.4
LM324NE4	N	PDIP	14	25	506	13.97	11230	4.32
LM324NE4	N	PDIP	14	25	506	13.97	11230	4.32
LM324PW	PW	TSSOP	14	90	530	10.2	3600	3.5

# FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# W (R-GDFP-F14)

## CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a ceramic its using glass mit.
   Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
   Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



## D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



# D (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



# PW (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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